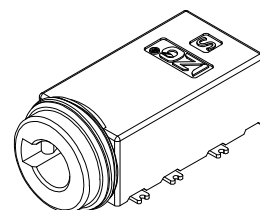
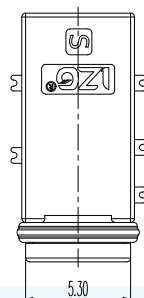
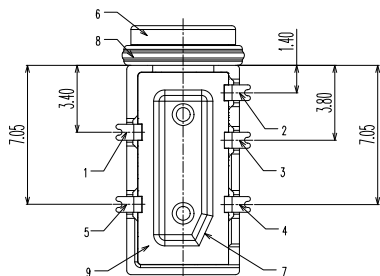


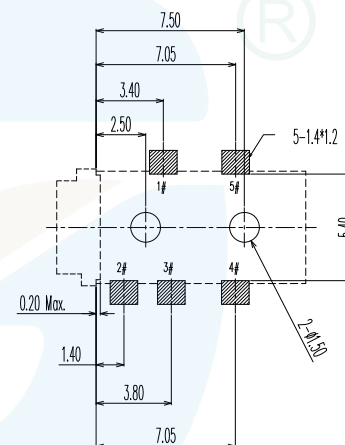
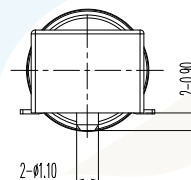
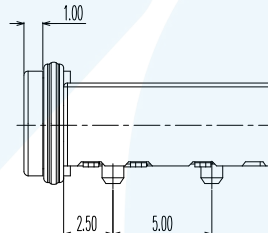
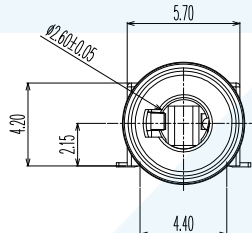
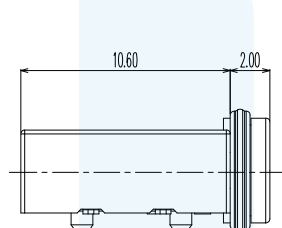
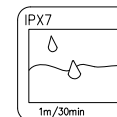
RoHS  
Compliant

| ZONE | ECN.N.O. | DESCRIPTION | DRAWING | DATE       |
|------|----------|-------------|---------|------------|
| A    |          | INITIAL     | 林生財     | 2023.12.18 |

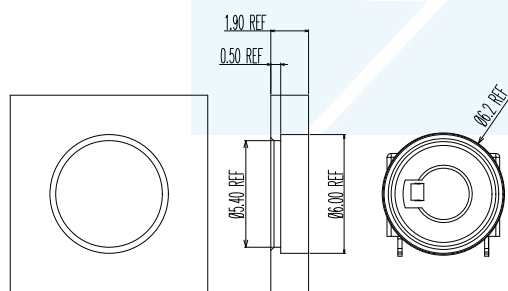


#### NOTES

1. CURRENT RATING: 1A.
2. CONTACT RESISTANCE: 100mΩ MAX.
3. INSULATION RESISTANCE: 100MΩ MIN.
4. DIELECTRIC WITHSTANDING: 500V AC MIN.
5. DURABILITY: 5000 CYCLES MIN.
6. CONNECTOR MATING FORCES: 3~30N.
7. CONNECTOR UNMATING FORCES: 3~30N.
8. OPERATING TEMPERATURE: -25°C TO +85°C.
9. WATERPROOF LEVEL: IP67



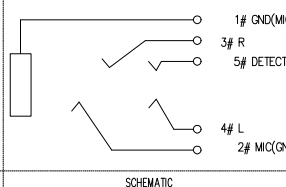
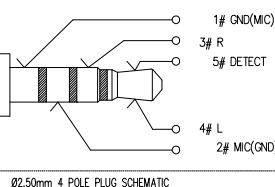
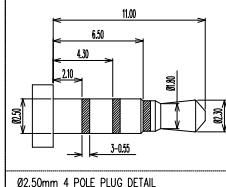
RECOMMEND PCB LAYOUT  
TOLERANCE: ±0.05



面板开孔参考尺寸

INSTALL WATERPROOF RING  
(UNCOMPRESSED)

Not to install the waterproof ring shipment



|      |                 |     |                                                                                               |
|------|-----------------|-----|-----------------------------------------------------------------------------------------------|
| 9    | GLUE            | 1   | EPPOXY, BLACK                                                                                 |
| 8    | WATERPROOF RING | 1   | SILICONE, BLACK                                                                               |
| 7    | COVER           | 1   | HIGH TEMPERATURE, BLACK                                                                       |
| 6    | HOUSING         | 1   | HIGH TEMPERATURE, BLACK                                                                       |
| 5    | TERMINAL 5#     | 1   | STAINLESS STEEL; NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA |
| 4    | TERMINAL 4#     | 1   | STAINLESS STEEL; NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA |
| 3    | TERMINAL 3#     | 1   | PHOSPHOR BRONZE; NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA |
| 2    | TERMINAL 2#     | 1   | PHOSPHOR BRONZE; NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA |
| 1    | TERMINAL 1#     | 1   | STAINLESS STEEL; NICKEL UNDERPLATING OVERALL, GOLD FLASH PLATING ON THE SOLDER & CONTACT AREA |
| ITEM | NAME            | QTY | DESCRIPTION                                                                                   |

**LZG**

LZG INDUSTRIAL CO. LTD

|             |                  |       |            |          |     |
|-------------|------------------|-------|------------|----------|-----|
| DRAWING:    | 林生財              | DATE: | 2023.12.18 | SCALE    | 1:1 |
| CHECK:      | 李宏鑫              | DATE: | 2023.12.18 | MATERIAL | *   |
| APPROVAL:   | 楊維安              | DATE: | 2023.12.18 | DWG. NO. |     |
| DRAWING NO. | ZB20001-05SBAP-A |       |            | SHEET    | 1/1 |

|           |                           |
|-----------|---------------------------|
| PART NAME | Ø2.5 PHONE JACK CONNECTOR |
| PART NO.  | ZB20001-05SBAP-A          |

|                      |                         |
|----------------------|-------------------------|
| TOLERANCE UNLESS     | 0.0±0.25                |
| OTHERWISE SPECIFIED: | 0.00±0.15<br>0.000±0.05 |

|            |
|------------|
| 0.1±2°     |
| 0.0°±1°    |
| 0.00°±0.5° |

|       |    |
|-------|----|
| UNIT: | mm |
|-------|----|

